

N-channel TrenchMOS standard level FET

Rev. 01 — 1 July 2010

Product data sheet

1. Product profile

1.1 General description

Standard level gate drive N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using advanced TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in high performance automotive applications.

1.2 Features and benefits

- AEC Q101 compliant
- Avalanche robust

1.3 Applications

- 12V Motor, lamp and solenoid loads
- High performance automotive power systems

- Suitable for standard level gate drive
- Suitable for thermally demanding environment up to 175°C rating
- High performance Pulse Width Modulation (PWM) applications

nexperia

1.4 Quick reference data

Table 1. Quick reference data

$\begin{array}{c c c c c c c } V_{DS} & drain-source \\ voltage \\ \hline \end{tabular} V_{GS} & figure \\ \hline \end{tabular} V_{MD} & figure \\ \hline \end{tabular} V_{GS} & figure \\ \hline \end{tabular} V_{G$								
voltageVIpdrain currentVVGS = 10 V; Tj = 25 °C;[1]Ptottotal power dissipationTTmb = 25 °C; see Figure 2 dissipationStatic characteristicsRDSondrain-source on-state resistanceVGS = 10 V; Ip = 25 A; resistance3.84.5rAvalanche ruggednessEDS(AL)Snon-repetitive drain-source avalanche energyIp = 75 A; VSubscienceIp = 75 A; V329rOgpgate-drain chargeVVGS = 10 V; Ip = 25 A; Tj(init) = 25 °C; unclamped21-rrOgpgate-drain chargeVVGS = 10 V; Ip = 25 °C;-2121-r	Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$\begin{array}{c c c c c c c } \hline & \text{see Figure 1} \\ \hline & \text{Ptot} & \text{total power} & \text{T}_{mb} = 25 ^{\circ}\text{C}; \text{see Figure 2} & - & - & 157 ^{\circ}\text{V} \\ \hline & \text{sissipation} \\ \hline & \text{Static characteristics} \\ \hline & \text{R}_{DSon} & \text{drain-source} & V_{GS} = 10 ^{\circ}\text{V}; ^{I}\text{I}\text{D} = 25 ^{\circ}\text{C}; \text{see Figure 12}; \\ & \text{on-state} & \text{T}_{j} = 25 ^{\circ}\text{C}; \text{see Figure 12}; \\ & \text{resistance} & \text{see Figure 13} \\ \hline & \text{Avalanche ruggedness} \\ \hline & \text{E}_{DS(AL)S} & \text{non-repetitive} & \text{I}_{D} = 75 ^{\circ}\text{A}; ^{\vee}\text{V}_{SS} = 10 ^{\vee}\text{V}; ^{\circ}\text{G} = 10 ^{\vee}\text{V}; \\ & \text{drain-source} & \text{R}_{GS} = 50 ^{\circ}\text{C}; ^{\circ}\text{uclamped} \\ \hline & \text{Dynamic characteristics} \\ \hline & \text{Q}_{GD} & \text{gate-drain charge} & \text{V}_{GS} = 10 ^{\vee}\text{V}; ^{I}\text{I}\text{D} = 25 ^{\circ}\text{C}; \\ \hline & \text{V}_{DS} = 24 ^{\vee}\text{V}; ^{I}\text{J} = 25 ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 10 ^{\vee}\text{C}; \\ \hline & \text{C}_{S} = 10 ^{\vee}\text{C}; ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 10 ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 24 ^{\vee}\text{V}; ^{I}\text{J} = 25 ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 24 ^{\vee}\text{C}; ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 24 ^{\vee}\text{C}; ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 25 ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 10 ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 24 ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 25 ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 24 ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 25 ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 10 ^{\circ}\text{C}; \\ \hline & \text{C}_{S} = 25 ^{$	V _{DS}		T _j ≥ 25 °C; T _j ≤ 175 °C		-	-	30	V
dissipationStatic characteristics R_{DSon} drain-source on-state resistance $V_{GS} = 10 \text{ V}; \text{ I}_D = 25 \text{ A};$ $T_j = 25 °C; \text{ see Figure 12};$ resistance-3.84.5rAvalanche ruggedness $E_{DS(AL)S}$ non-repetitive drain-source avalanche energyID T = 75 A; $V_{sup} \le 30 \text{ V};$ $T_{j(init)} = 25 °C;$ unclamped329rDynamic characteristics Q_{GD} gate-drain charge $V_{GS} = 10 \text{ V};$ $V_{DS} = 24 \text{ V};$ $T_j = 25 °C;$ -21-r	I _D	drain current	,	<u>[1]</u>	-	-	75	A
$ \begin{array}{c} R_{DSon} & \mbox{drain-source} & V_{GS} = 10 \ V; \ I_D = 25 \ A; & - & 3.8 & 4.5 \ r \\ \hline r_j = 25 \ ^\circ C; \ see \ \overline{Figure} \ 12; \\ resistance & see \ \overline{Figure} \ 13 \end{array} \\ \begin{array}{c} \textbf{Avalanche ruggedness} \\ \hline \textbf{Avalanche ruggedness} \\ \hline \textbf{E}_{DS(AL)S} & \ non-repetitive & \ I_D = 75 \ A; \ V_{sup} \le 30 \ V; & - & - & 329 \ r \\ \ drain-source & \ R_{GS} = 50 \ \Omega; \ V_{GS} = 10 \ V; \\ avalanche energy & \ T_{j(\text{init})} = 25 \ ^\circ C; \ unclamped \end{array} \\ \begin{array}{c} \textbf{Dynamic characteristics} \\ \hline \textbf{Q}_{GD} & \ gate-drain charge & \ V_{GS} = 10 \ V; \ I_D = 25 \ A; \\ \ V_{DS} = 24 \ V; \ T_j = 25 \ ^\circ C; \end{array} \end{array}$	P _{tot}		T _{mb} = 25 °C; see <u>Figure 2</u>		-	-	157	W
$\begin{array}{c} \text{on-state} & \text{T}_{j} = 25 \ ^{\circ}\text{C}; \ \text{see} \ \overline{Figure \ 12}; \\ \text{resistance} & \text{see} \ \overline{Figure \ 13} \end{array}$ $\begin{array}{c} \textbf{Avalanche ruggedness} \\ \hline \textbf{Avalanche ruggedness} \\ \hline \textbf{E}_{DS(AL)S} & \text{non-repetitive} & \textbf{I}_{D} = 75 \ \text{A}; \ V_{sup} \le 30 \ \text{V}; & - & - & 329 \ \text{r} \\ \text{drain-source} & \textbf{R}_{GS} = 50 \ \Omega; \ V_{GS} = 10 \ \text{V}; \\ \text{avalanche energy} & \textbf{T}_{j(\text{init})} = 25 \ ^{\circ}\text{C}; \ \text{unclamped} \end{array}$ $\begin{array}{c} \textbf{Dynamic characteristics} \\ \hline \textbf{Q}_{GD} & \text{gate-drain charge} & V_{GS} = 10 \ \text{V}; \ \textbf{I}_{D} = 25 \ \text{C}; \\ V_{DS} = 24 \ \text{V}; \ \textbf{T}_{j} = 25 \ ^{\circ}\text{C}; \end{array}$	Static cha	racteristics						
$ \begin{array}{c} E_{DS(AL)S} & \mbox{non-repetitive} & \mbox{I}_D = 75 \ A; \ V_{sup} \leq 30 \ V; & - & - & 329 \ rr \\ & \mbox{drain-source} & & \mbox{R}_GS = 50 \ \Omega; \ V_GS = 10 \ V; \\ & \mbox{avalanche energy} & \mbox{T}_{j(\text{init})} = 25 \ ^\circC; \ unclamped \\ \end{array} $	R _{DSon}	on-state	$T_j = 25 \text{ °C}; \text{ see } Figure 12;$		-	3.8	4.5	mΩ
$\begin{array}{c} \mbox{drain-source} & R_{GS} = 50 \ \Omega; \ V_{GS} = 10 \ V; \\ \mbox{avalanche energy} & T_{j(init)} = 25 \ ^{\circ}C; \ unclamped \end{array}$	Avalanche	e ruggedness						
	E _{DS(AL)S}	drain-source	$R_{GS} = 50 \Omega; V_{GS} = 10 V;$		-	-	329	mJ
$V_{\rm DS} = 24 \text{ V}; \text{ T}_{\rm j} = 25 \text{ °C};$	Dynamic o	characteristics						
	Q _{GD}	gate-drain charge	$V_{DS} = 24 \text{ V}; \text{ T}_{j} = 25 \text{ °C};$		-	21	-	nC

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[1] Continuous current is limited by package.

2. Pinning information

Table 2.	Pinning	information		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		-
2	D	drain ^[1]	mb	
3	S	source		
mb	D	mounting base; connected to drain		mbb076 S
			SOT428 (DPAK)	

[1] It is not possible to make connection to pin 2.

3. Ordering information

Table 3.Ordering information

Type number	Package		
	Name	Description	Version
BUK724R5-30C	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	SOT428

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4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C		-	-	30	V
V _{DGR}	drain-gate voltage	R _{GS} = 20 kΩ		-	-	30	V
V _{GS}	gate-source voltage			-20	-	20	V
I _D	drain current	V_{GS} = 10 V; T _j = 25 °C; see <u>Figure 1</u> ; see <u>Figure 4</u>	<u>[1]</u>	-	-	136	A
		T_{mb} = 100 °C; V_{GS} = 10 V; see Figure 1	[2]	-	-	75	А
		V_{GS} = 10 V; T _j = 25 °C; see <u>Figure 1</u>	[2]	-	-	75	А
I _{DM}	peak drain current	t _p ≤ 10 μs; pulsed; T _j = 25 °C; see <u>Figure 4</u>		-	-	543	A
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>		-	-	157	W
T _{stg}	storage temperature			-55	-	175	°C
Tj	junction temperature			-55	-	175	°C
Source-drain	diode						
I _S	source current	T _{mb} = 25 °C	[2]	-	-	75	А
			[1]	-	-	136	А
I _{SM}	peak source current	$t_p \le 10 \ \mu s$; pulsed; $T_{mb} = 25 \ ^{\circ}C$		-	-	543	А
Avalanche rug	ggedness						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	$\label{eq:ID} \begin{array}{l} I_D = 75 \text{ A}; \ V_{sup} \leq 30 \text{ V}; \ R_{GS} = 50 \ \Omega; \\ V_{GS} = 10 \text{ V}; \ T_{j(init)} = 25 \ ^\circ\text{C}; \ unclamped \end{array}$		-	-	329	mJ
E _{DS(AL)R}	repetitive drain-source avalanche energy	see Figure 3	<u>[3][4][5]</u>	-	-	-	J

[1] Current is limited by power dissipation chip rating.

[2] Continuous current is limited by package.

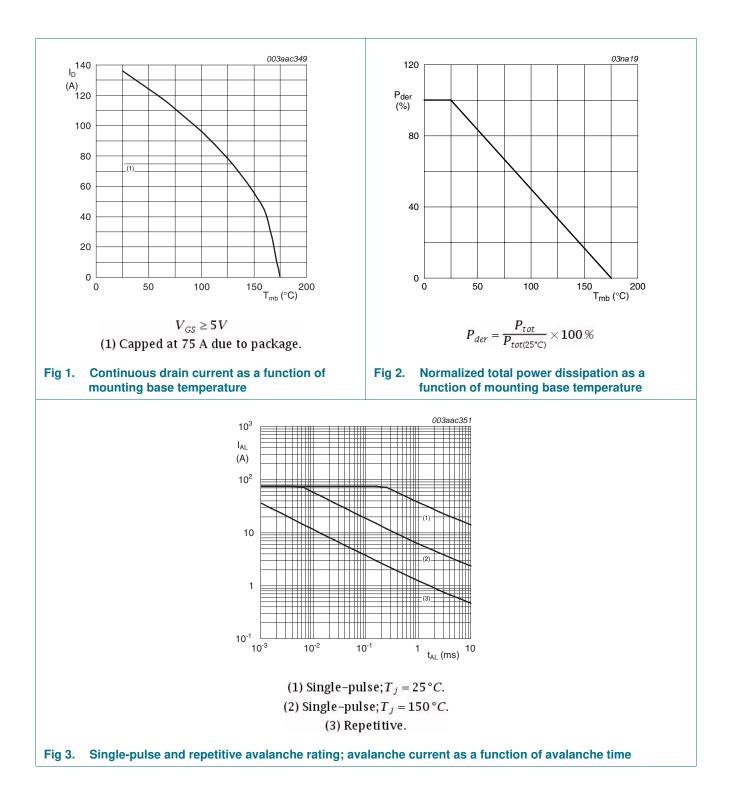
[3] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.

[4] Repetitive avalanche rating limited by average junction temperature of 170 °C.

[5] Refer to application note AN10273 for further information.

BUK724R5-30C

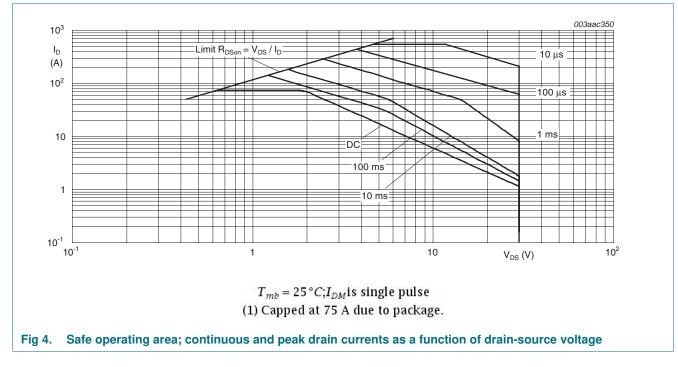
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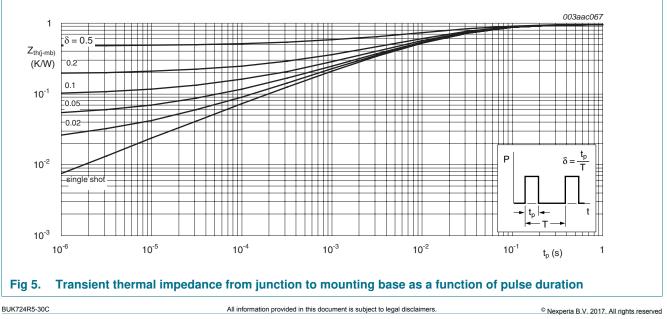
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5. Thermal characteristics

Table 5.	Thermal characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{\text{th(j-mb)}}$	thermal resistance from junction to mounting base	see <u>Figure 5</u>	-	0.65	0.95	K/W
R _{th(j-a)}	thermal resistance from junction to ambient		-	70	-	K/W



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6. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	cteristics					
V _{(BR)DSS}	drain-source	I _D = 0.25 mA; V _{GS} = 0 V; T _i = 25 °C	30	-	-	V
()	breakdown voltage	I _D = 0.25 mA; V _{GS} = 0 V; T _i = -55 °C	27	-	-	V
V _{GS(th)}	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ °C};$ see <u>Figure 10</u> ; see <u>Figure 11</u>	2	3	4	V
		I _D = 1 mA; V _{DS} = V _{GS} ; T _j = 175 °C; see <u>Figure 10</u>	1	-	-	V
		I _D = 1 mA; V _{DS} = V _{GS} ; T _j = -55 °C; see <u>Figure 10</u>	-	-	4.4	V
I _{DSS}	drain leakage current	V _{DS} = 30 V; V _{GS} = 0 V; T _j = 175 °C	-	-	500	μA
		V_{DS} = 30 V; V_{GS} = 0 V; T_j = 25 °C	-	0.02	1	μA
I _{GSS}	gate leakage current	V_{DS} = 0 V; V_{GS} = 20 V; T_j = 25 °C	-	2	100	nA
		V _{DS} = 0 V; V _{GS} = -20 V; T _j = 25 °C	-	2	100	nA
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 25 A; T _j = 175 °C; see <u>Figure 12</u>	-	-	8.5	mΩ
		V _{GS} = 10 V; I _D = 25 A; T _j = 25 °C; see <u>Figure 12</u> ; see <u>Figure 13</u>	-	3.8	4.5	mΩ
Dynamic ch	aracteristics					
Q _{G(tot)}	total gate charge	$I_D = 25 \text{ A}; V_{DS} = 24 \text{ V}; V_{GS} = 10 \text{ V};$ $T_j = 25 \text{ °C}; \text{ see } \frac{\text{Figure } 14}{14}$	-	62	-	nC
Q _{GS}	gate-source charge	I _D = 25 A; V _{DS} = 24 V; V _{GS} = 10 V; T _j 25 °C; see <u>Figure 14</u>	-	14	-	nC
Q _{GD}	gate-drain charge	I _D = 25 A; V _{DS} = 24 V; V _{GS} = 10 V; T _j = 25 °C; see <u>Figure 14</u>	-	21	-	nC
C _{iss}	input capacitance	V_{GS} = 0 V; V_{DS} = 25 V; f = 1 MHz;	-	2820	3760	pF
C _{oss}	output capacitance	$T_j = 25 \text{ °C}; \text{ see } \frac{\text{Figure } 15}{15}$	-	670	804	pF
C _{rss}	reverse transfer capacitance		-	422	580	pF
t _{d(on)}	turn-on delay time		-	24	-	ns
t _r	rise time	$V_{DS} = 25 \text{ V}; \text{ R}_{L} = 1 \Omega; V_{GS} = 10 \text{ V}; \text{ R}_{G(ext)} 10 \Omega; \text{ T}_{j} = 25 ^{\circ}\text{C}$	-	51	-	ns
d(off)	turn-off delay time	V_{DS} = 25 V; R_{L} = 1 Ω ; V_{GS} = 10 V;	-	85	-	ns
f	fall time	R _{G(ext)} = 10 Ω; T _j = 25 °C	-	62	-	ns
-D	internal drain inductance	measured from drain to centre of die ; T_j = 25 $^\circ\text{C}$	-	2.5	-	nH
L _S	internal source inductance	measured from source lead to source bond pad ; T _i = 25 °C	-	7.5	-	nH

Symbol

BUK724R5-30C

Unit

Max

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Тур

Min

Source-dra	ain diada						
		1 - 20 $(1) - 0)$	/. T _ 25 °C.		0.05	10	\ <i>\</i>
V _{SD}	source-drain voltage	I _S = 20 A; V _{GS} = 0 \ see <u>Figure 16</u>	, 1 _j = 25°C,	-	0.85	1.2	V
rr	reverse recovery time	$I_{S} = 20 \text{ A}; \text{ d}I_{S}/\text{d}t = -2$	100 A/µs;	-	40	-	ns
Qr	recovered charge	V _{GS} = -10 V; V _{DS} =	25 V; T _j = 25 °C	-	44	-	nC
		003aac408				003aac353	
400	15		80				
	20		(A)		/	1	
(A)	10						
300 -	V _{GS} = 7.5 (V)		60				
	V _{GS} = 7.5 (V)				+//		
200		7	40				
200		6	40	T _i = 175 °C	11		
-							
100		5.5	20		∕⊥/		
		5			25	°C	
-		4.5					
14							
0		8 10	0	0		~	
0	0 2 4 6	8 10 V _{DS} (V)	0	2	4 V _{GS}	(V) 6	
	$T_j = 25 ^{\circ}C$	8 10 V _{DS} (V)	0		• 65	, (V) 6	
0	$T_j = 25 ^{\circ}C$		0	$V_{DS} = 25 V$	/		
0 Fig 6. O	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a	0 Fig 7. Transfer c	$V_{DS} = 25 V_{DS}$	/ : drain c	current a	
0 Fig 6. O	$T_j = 25 ^{\circ}C$	n current as a tage; typical values	0 Fig 7. Transfer c	$V_{DS} = 25 V$	/ : drain c voltage;	current a ; typical	
0 Fig 6. O	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a	0 Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a	
6 Fig 6. O fu	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a tage; typical values	0 Fig 7. Transfer of function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a ; typical	
0 Fig 6. O fu	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a tage; typical values	0 Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a ; typical	
6 Fig 6. O fu	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a tage; typical values	0 Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a ; typical	
6 Fig 6. O fu	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a tage; typical values	0 Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a ; typical	
Fig 6. O fu g _{fs} (S) 60	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a tage; typical values	0 Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a ; typical	
6 Fig 6. O fu	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a tage; typical values	0 Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a ; typical	
Fig 6. O fu g _{fs} (S) 60	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a tage; typical values	0 Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a ; typical	
Fig 6. O fu g _{fs} (S) 60 40	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a tage; typical values	0 Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a ; typical	
Fig 6. O fu g _{fs} (S) 60	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a tage; typical values	0 Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a ; typical	
Fig 6. O fu g _{fs} (S) 60 40	$T_j = 25 ^{\circ}C$ Output characteristics: drain	n current as a tage; typical values	0 Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ : drain c voltage;	current a ; typical	
Fig 6. O fu g _{fs} (S) 60 40 20	$T_j = 25 ^{\circ}C$	003aac422	0 Fig 7. Transfer c function o	V _{DS} = 25V	/ contage:	2003aac421	values
Fig 6. O fu grs (S) 60 40 20	$T_j = 25 ^{\circ}C$	n current as a tage; typical values	C Fig 7. Transfer c function o	$V_{DS} = 25 V_{DS}$	/ contage:	current a ; typical	values
Fig 6. O fu g _{fs} (S) 60 40 20	$T_j = 25 ^{\circ}C$	003aac422	⁰ Fig 7. Transfer c function o	V _{DS} = 25V	/ contractions	2003aac421	values
Fig 6. O fu g _{fs} (S) 60 40 20 0 0	$T_j = 25 ^{\circ}C$	003aac422	⁰ Fig 7. Transfer c function o	V _{DS} = 25 V	<pre>// : drain c voltage; //</pre>	2003aac421	values

Table 6. Characteristics ...continued

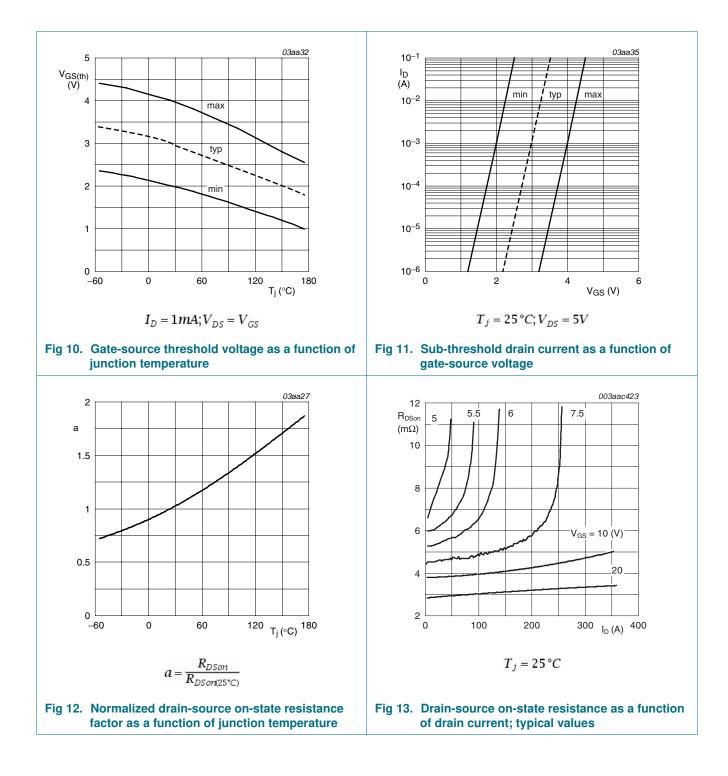
Parameter

Conditions

BUK724R5-30C

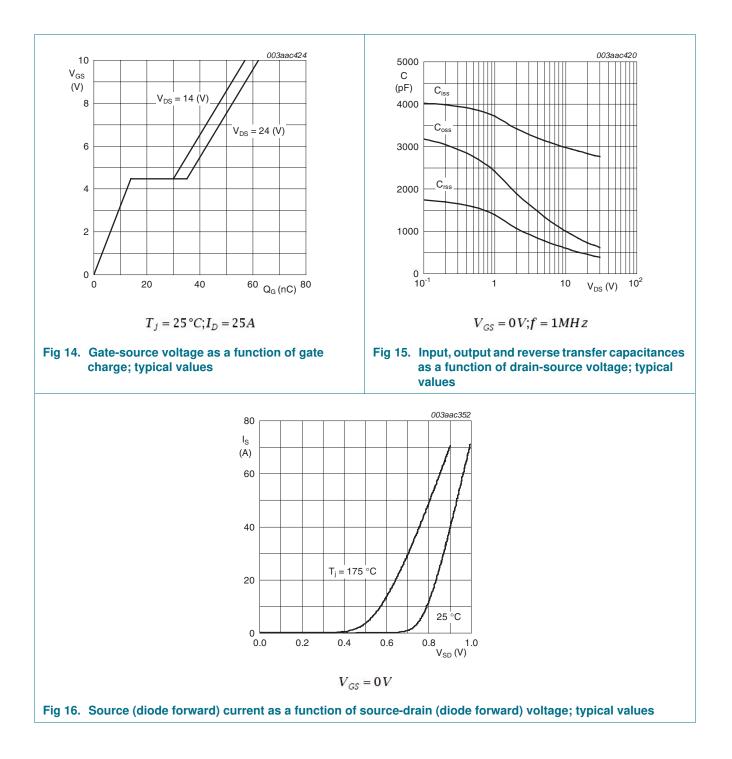
BUK724R5-30C

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BUK724R5-30C

N-channel TrenchMOS standard level FET



BUK724R5-30C

N-channel TrenchMOS standard level FET

7. Package outline

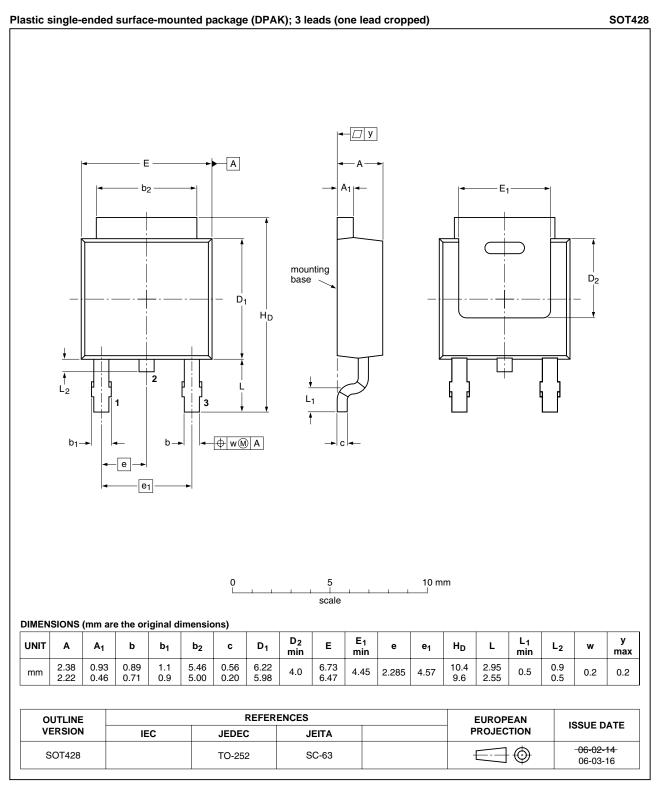


Fig 17. Package outline SOT428 (DPAK)

BUK724R5-30C Product data sheet

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8. Revision history

Table 7. Revision his	tory			
Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK724R5-30C v.1	20100701	Product data sheet	-	-

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9. Legal information

9.1 Data sheet status

Document status[1][2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <u>http://www.nexperia.com</u>.

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10. Contact information

For more information, please visit: http://www.nexperia.com

For sales office addresses, please send an email to: salesaddresses@nexperia.com

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